


# MATERIAL DECLARATION SHEET



Material Number	<b>CRP0603-LF</b>			
Product Line	<b>High precision chip resistors</b>			
Compliance Date	<b>4-1-03</b>			
RoHS Compliant	<b>Yes (Lead Exemption)</b>	MSL	<b>1</b>	

No.	Construction Element(subpart)	Homogeneous Material	Material weight [mg]	Homogeneous Material\ Substances	CASRN if applicable	Materials Mass %	Material Mass % of total unit wt.	Subpart mass of total wt. (%)
1	Ceramic	Substrate	1.8110	Aluminum oxide	1344-28-1	96	77.316	80.536
				Silicon dioxide	7631-86-9	4	3.220	
				Magnesium oxide	1309-48-4			
2	Top conductor	Silver	0.0464	Silver	7440-22-4	100	2.063	2.063
3	Bottom conductor	Silver	0.0201	Silver	7440-22-4	100	0.894	0.894
4	Resistor	Ruthenium Oxide	0.0264	Silver	7440-22-4	40	0.467	1.174
				Ruthenium dioxide	12036-10-1	20	0.236	
				Palladium	7440-05-3	15	0.178	
				Glass	65997-18-4	14.9	0.175	
				Lead oxide	1317-36-8	10.1	0.118	

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5	First encapsulating	Resin	0.0252	Bismuth trioxide	1304-76-3	50	0.560	1.120
				Epoxy resin	25036-25-3	30	0.338	
				Aluminum oxide	1344-28-1	10	0.111	
				Boron oxide	1303-86-2	10	0.111	
6	Overcoat	Resin	0.0517	Epoxy resin	25036-25-3	100	2.299	2.299
7	Side conductor	Silver	0.1309	Silver	7440-22-4	85	4.949	5.821
				Phenolic resin	9003-36-5	15	0.872	
8	Plating (Middle)	Nickel	0.0525	Nickel	7440-02-0	100	2.335	2.335
9	Plating (Outer)	Tin	0.0782	Tin	7440-31-5	100	3.478	3.478
10	Marking	Resin	0.0063	Epoxy	25068-38-6	70	0.196	0.280
				Titanium dioxide	1317-80-2	30	0.084	
Total weight			2.2487					

**This Document was updated on: 1-27-2012**

**Important remarks:**

1. It is the responsibility of the user to verify they are accessing the latest version.
2. RoHS exemption: 7(c)-I – electrical and electronic components containing lead in a glass or ceramic...